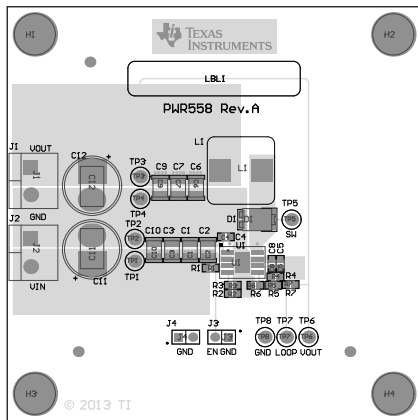


Layer Stack Up Detail for: PWR558h_pcb.PcbDoc			
Layer Name	Order	Copper Thickness	Dielectric Material
Top Solder Mask	1.0150		Solder Resist
Top Layer	1.0151	1.4mil	FR-4
Mid.Layer1	1.0152	1.4mil	FR-4
Mid.Layer2	1.0153	1.4mil	FR-4
Bottom Layer	1.0154	1.4mil	FR-4
Bottom Solder Mask	1.0155		Solder Resist

- ZZ1 ■ Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per Table 1
- ZZ2 ■ These assemblies are ESD sensitive. ESD precautions shall be observed.
- ZZ3 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- ZZ4 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

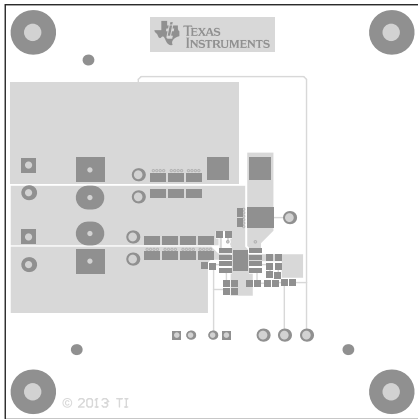


ET-HS
SH-J3

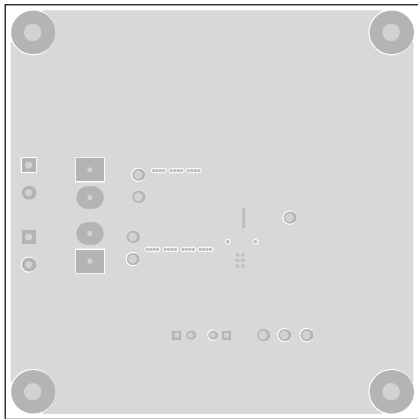
TABLE 1	
Variant	Label text
Standard Assembly	TP554540EUP-558

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED, AND MAY NOT BE IN BILL OF MATERIALS
ASSEMBLY VARIANT: [No Variations]

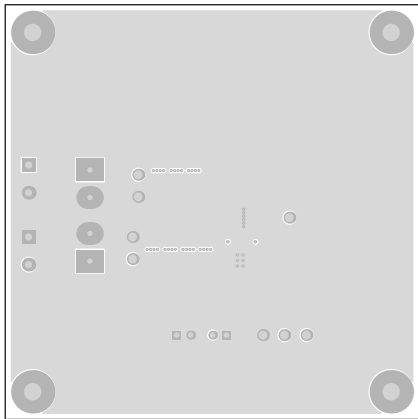
PCB VIEWED FROM TOP SIDE	BOARD #: PWR558	REV: A	SUN REV: Not In VersionControl
IGNORE -> Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 6/3/2013	1:11:21 PM	TEXAS INSTRUMENTS



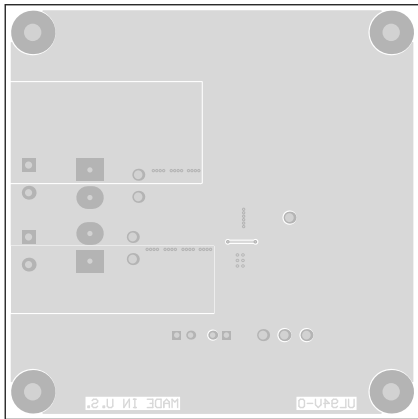
Top Solder



MI Board Outline



MI Board Outline



Bottom Layer

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